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(54) Title: SUBSTRATE EDGE PROFILE TREATMENT

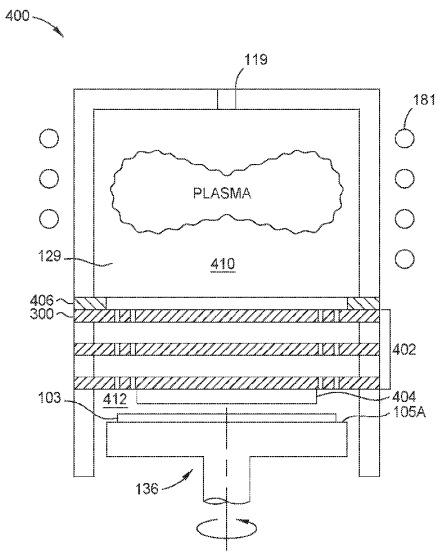


FIG. 4

(57) Abstract: Embodiments described herein relate to a method of treatment for substrate edge profiles. The method including generating a plasma in a plasma processing region of a processing volume of a processing chamber where the processing volume includes a first volume disposed above a grid assembly to receive the plasma and a second volume containing a substrate support assembly disposed below the grid assembly for processing a substrate. The grid assembly includes one or more grid plates; each grid plate including a plurality of perforations of two or more perforations arranged along a circular path disposed over a peripheral region of a substrate support surface. The method includes exposing the peripheral region of the substrate support surface to a plasma species generated in the first volume by focusing the plasma species through the perforations onto the peripheral region of the substrate support surface in the second volume.

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